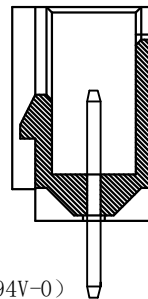
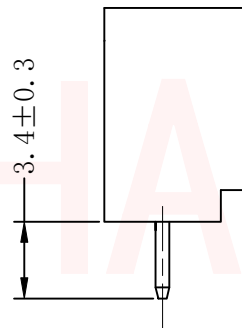
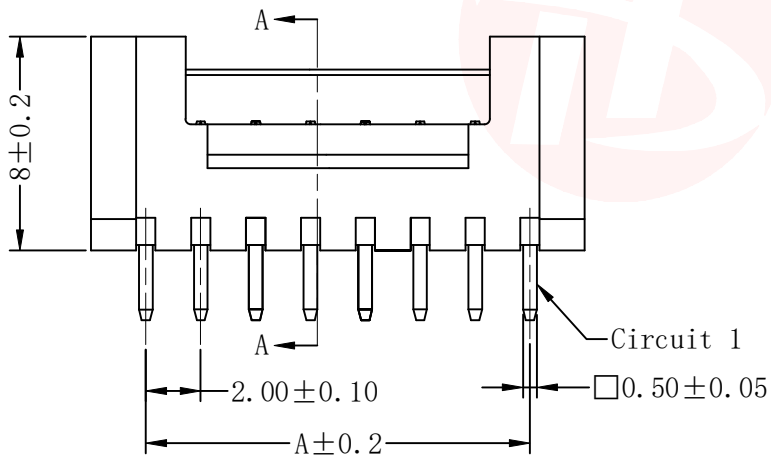
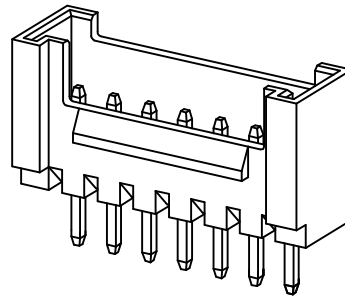
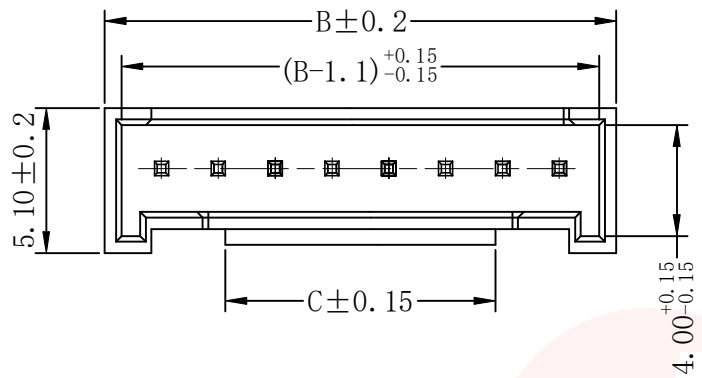
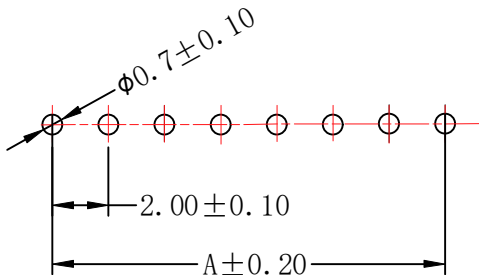




REV.	ECN NO OR DESCRIPTION	REVISED	DATE



SECTION A-A



SUGGESTED PCB LAYOUT
(COMPONENT SIDE)

技术要求:

- 1、塑件材料: LCP/PA66 (UL-94V-0)
- 2、接触件: 黄铜镀锡
- 3、接触电阻: $\leq 10\text{m}\Omega$
- 4、绝缘电阻: $\geq 1000\text{M}\Omega$
- 5、额定电压: 250V AC DC
- 6、额定电流: 2.0A AC DC
- 7、耐压: 能承受1000V AC/Minute
- 8、工作温度: $-25^{\circ} \sim +85^{\circ}$
- 9、可焊性试验: 浸锡面积 $\geq 95\%$ 温度 $220^{\circ}\pm 5^{\circ}$, 时间 2.5 ± 0.5 秒
- 10、铅和镉等六大有害物质含量要符合环保要求

TABLE:

CSG PART NO.	Dimension mm			
	PIN	A	B	C
WAFER-HY200Z-2A	2P	2.00	6.00	2.50
WAFER-HY200Z-3A	3P	4.00	8.00	2.50
WAFER-HY200Z-4A	4P	6.00	10.00	3.50
WAFER-HY200Z-5A	5P	8.00	12.00	5.50
WAFER-HY200Z-6A	6P	10.00	14.00	7.50
WAFER-HY200Z-7A	7P	12.00	16.00	9.50
WAFER-HY200Z-8A	8P	14.00	18.00	11.50
WAFER-HY200Z-9A	9P	16.00	20.00	13.50
WAFER-HY200Z-10A	10P	18.00	22.00	15.50
WAFER-HY200Z-11A	11P	20.00	24.00	15.50
WAFER-HY200Z-12A	12P	22.00	26.00	15.50
WAFER-HY200Z-13A	13P	24.00	28.00	15.50
WAFER-HY200Z-14A	14P	26.00	30.00	15.50
WAFER-HY200Z-15A	15P	28.00	32.00	15.50

序号	名称	材料	电镀(锡): 整个表面镀底镍 30U"MIN 再镀锡80U" MIN
1	端子/Contact	黄铜	
2	基座/Wafer	LCP/PA66 (UL94V-0)	白色

UNLESS OTHERWISE SPECIFIED TOLERANCES



东莞市汉博电子科技有限公司
DONGGUAN HANBO TECHNOLOGY CO., LTD

DECIMALS:	ANGLES:	TITLE	WAFER HY 2.0MM 直针 DIP TYPE		
X : ±0.20	X : ±2°	DWN	xiong	PART NO. WAFER-HY200Z-NA	
X.X : ±0.10	X.X : ±1°	CHKD	lee	SCALE: 1:1	UNIT: mm
X.XX : ±0.05		APVD	wang	SIZE: A4	SHEET: 10F 1
CUSTOMER COPY					